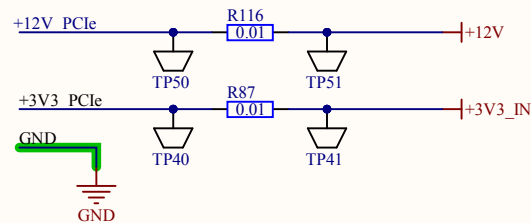
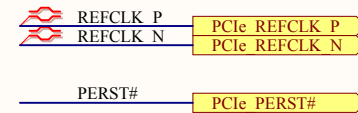
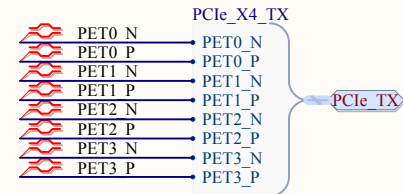
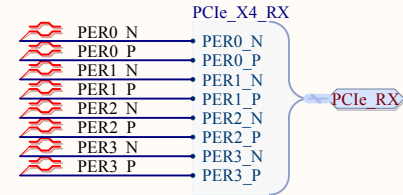
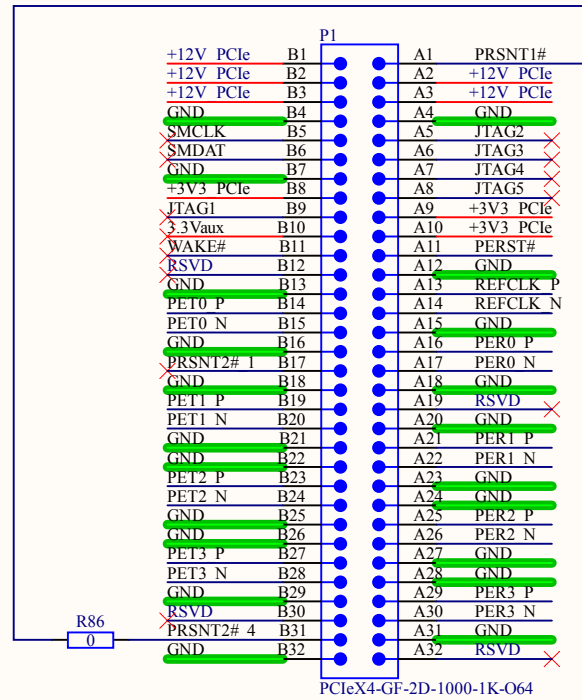


- Nominal values used, dimensions in mm
- The mounting holes and keep-out areas around them are only required when the I/O bracket is mounted on the card directly
- Component height rule and clearance rule derived from PCI_Express_CEM_r2.0.pdf, Page 84.
- Stackup is not specified in PCI_Express_CEM_r2.0.pdf, nor implemented in this template.



A

B

C

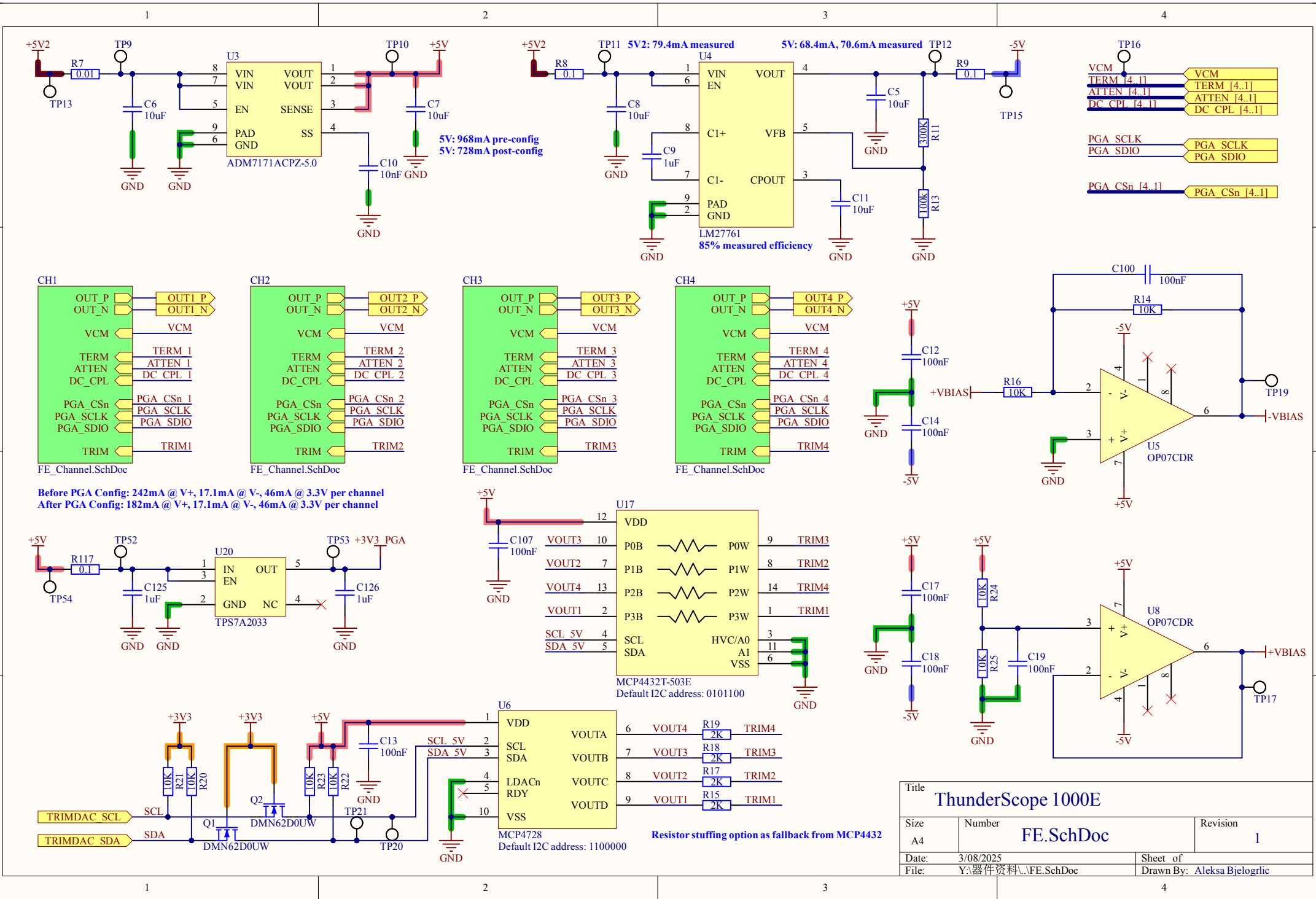
D

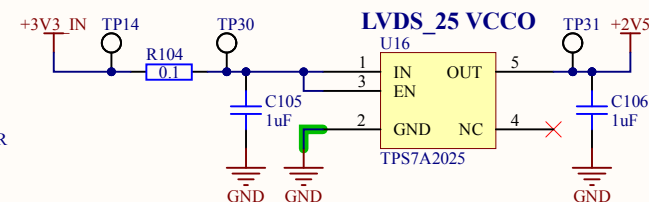
A

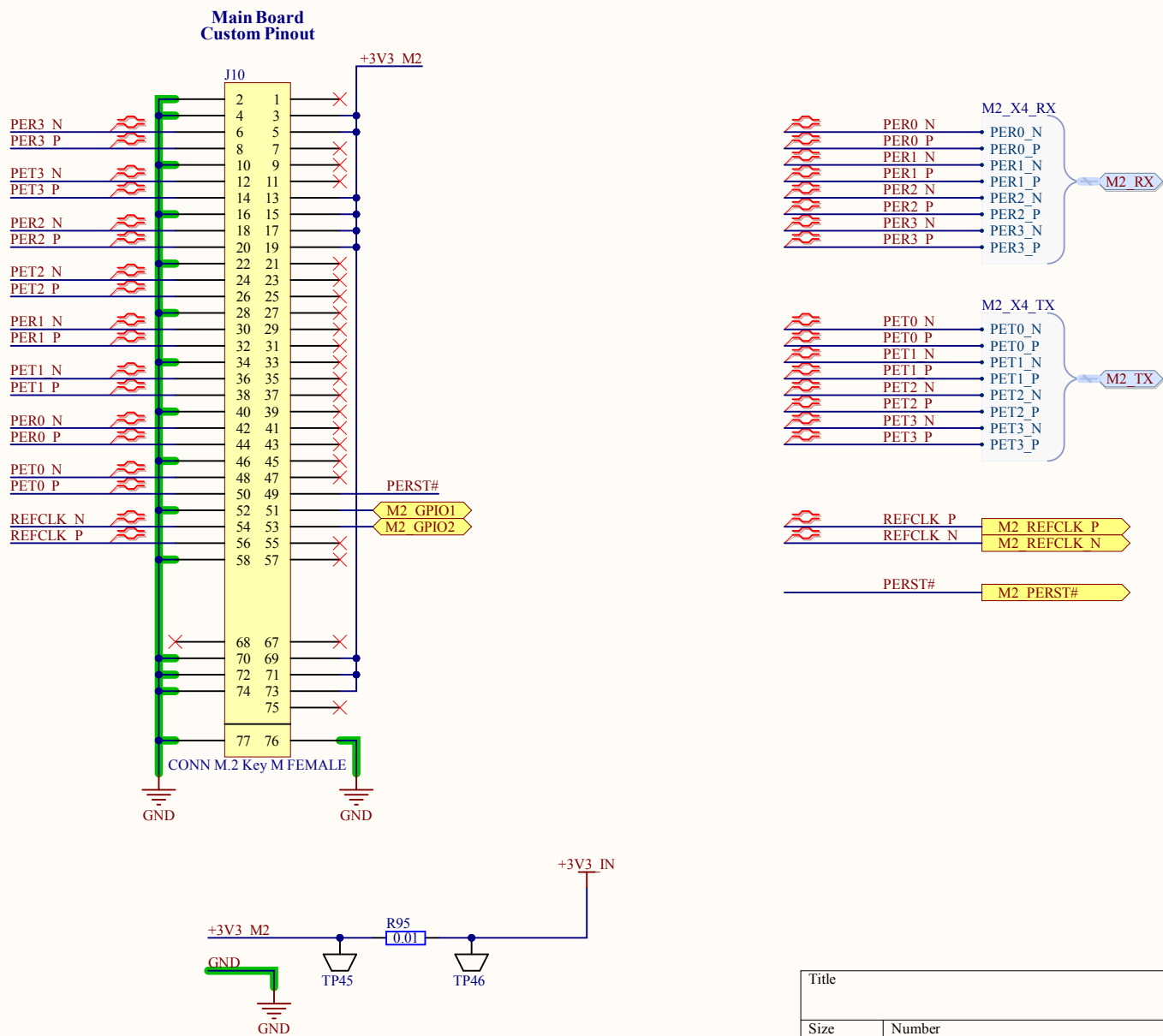
B

C

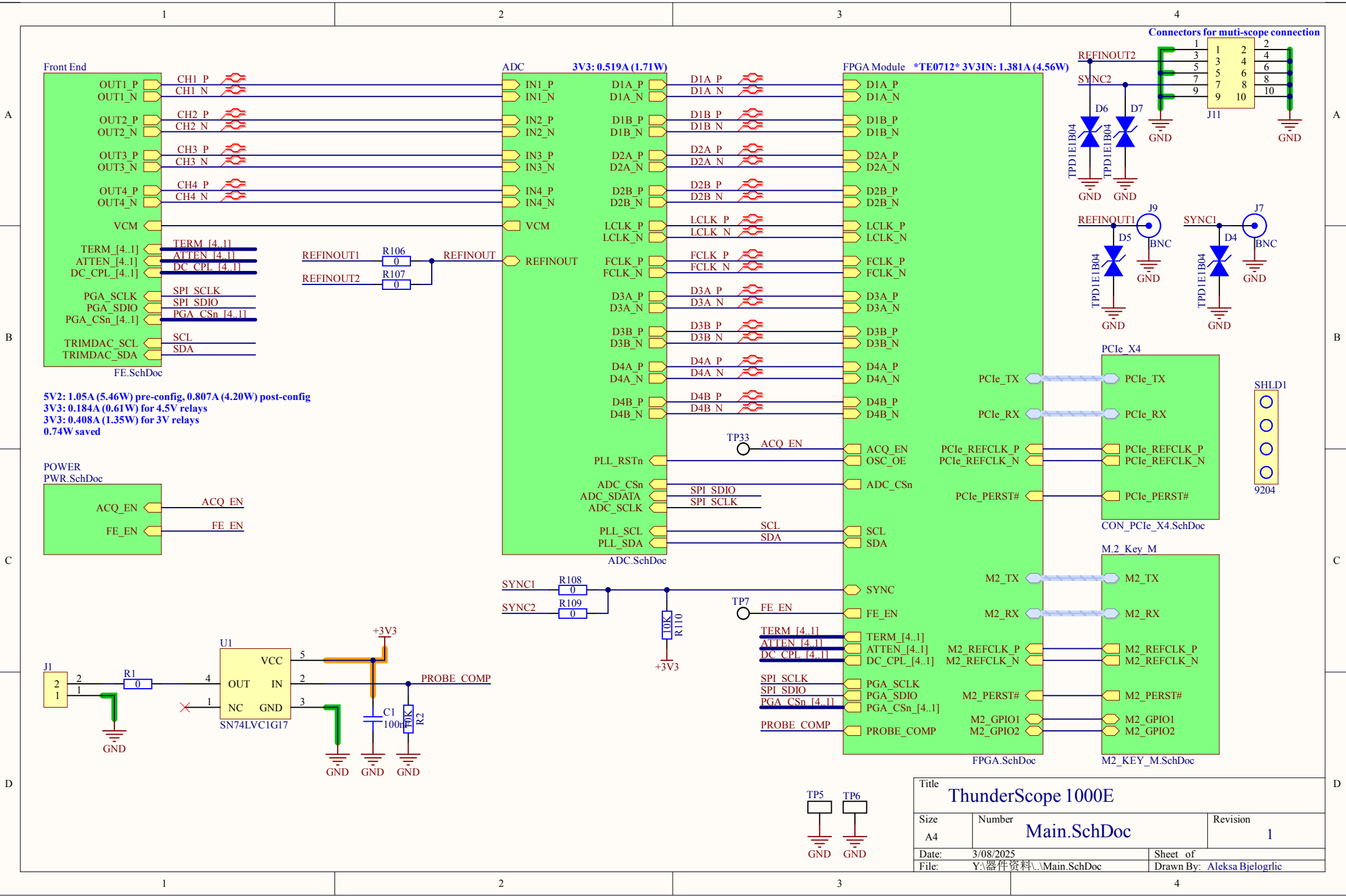
D







Title		
Size A4	Number	Revision
Date: 3/08/2025	Sheet of	
File: Y:\器件资料\AM2 KEY M.SchDoc	Drawn By:	

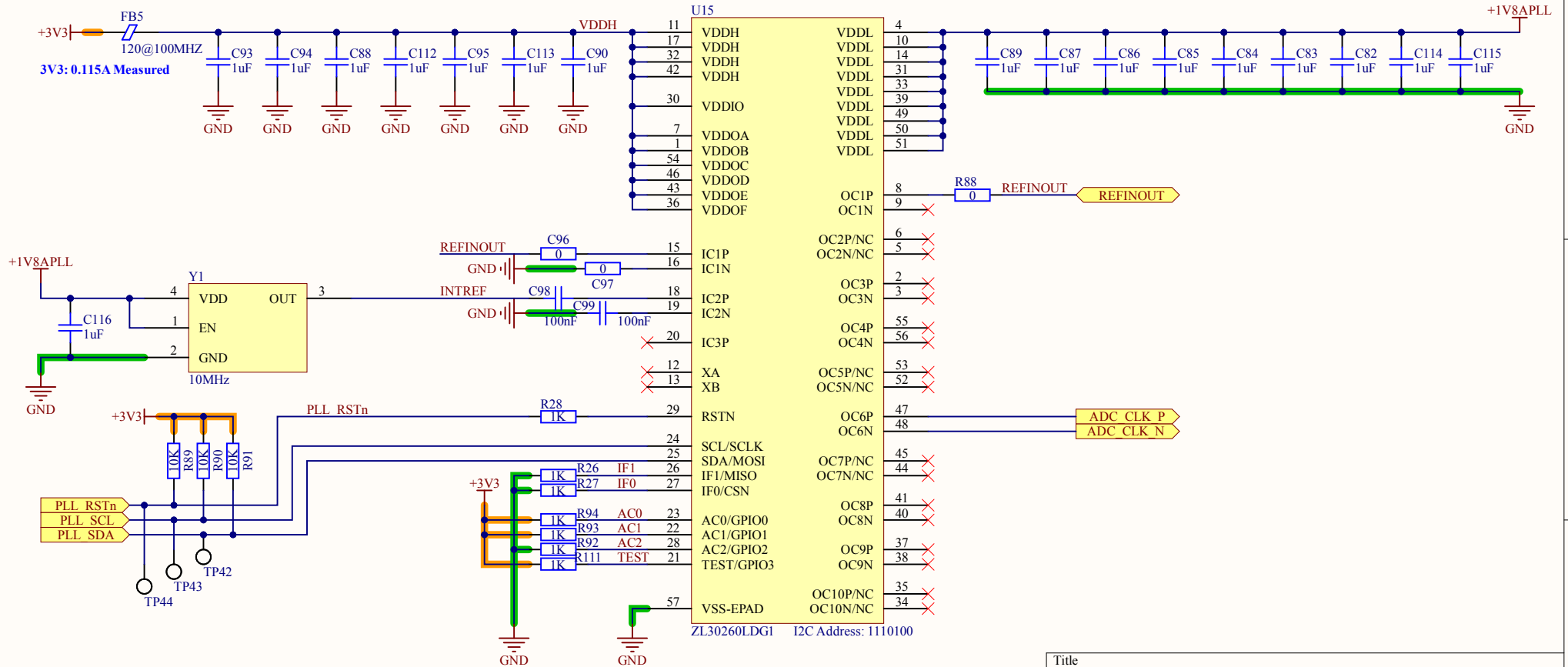


Title		
ThunderScope 1000E		
Size	Number	Revision
A4	Main.SchDoc	1
Date:	3/08/2025	Sheet of
File:	Y:\器件资料\Main.SchDoc	Drawn By: Aleksa Bjelogrić

IF1	IF0	Processor Interface	Configuration Memory to Use
0	0	I ² C, slave address 11101 00	Internal ROM
0	1	I ² C, slave address 11101 01	Internal ROM
1	0	SPI Slave	Internal ROM
1	1	SPI Master during auto-configuration then SPI Slave	External SPI EEPROM

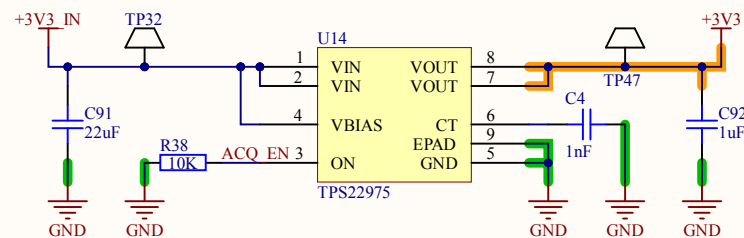
To configure the device as specified in the first three rows above but without auto-configuring from internal ROM, wire devices pins as follows: TEST=1 and AC[2:0]=011, as described in section 5.2.

AC2	AC1	AC0	Auto Configuration
0	0	0	Configuration 0
0	0	1	Configuration 1
0	1	0	Configuration 2
0	1	1	Configuration 3
1	0	0	Configuration 4
1	0	1	Configuration 5
1	1	0	Configuration 6
1	1	1	Configuration 7

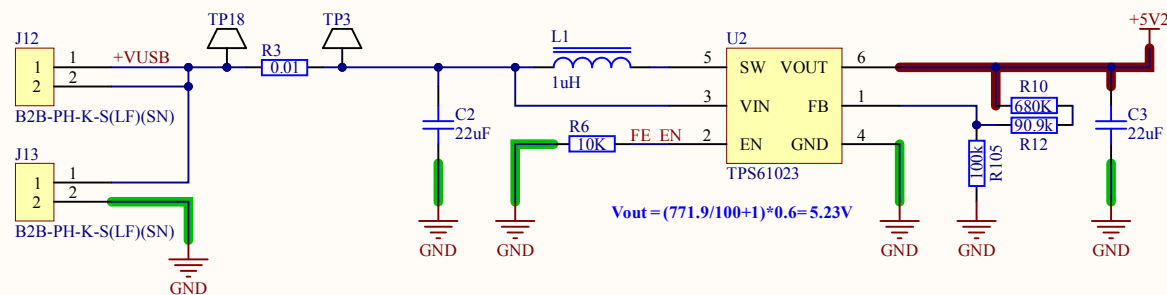


3.3 + 1.8V operation w/ one input one output: 0.67W Expected
0.62W Measured

Title		
Size	Number	Revision
A4		
Date:	3/08/2025	Sheet of
File:	Y:\器件资料\APLL.SchDoc	Drawn By:

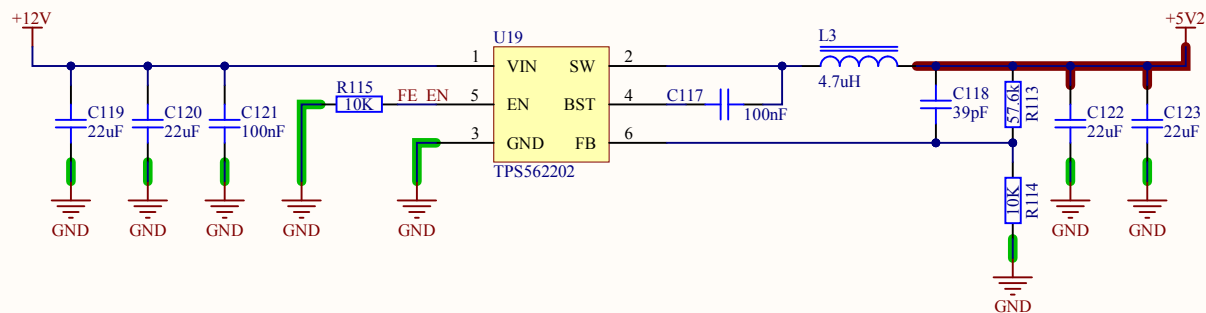


3V3: 0.703A (2.32W) for 4.5V relays
3V3: 0.927A (3.06W) for 3V relays



$$V_{out} = (771.9/100 + 1) * 0.6 = 5.23V$$

5V2: 1.05A pre-config, 0.807A post-config



Title		
Size	Number	Revision
A4		
Date:	3/08/2025	Sheet of
File:	Y:\器件资料\APWR.SchDoc	Drawn By:

